

Let's look at a special case of the Heat Diffusion Equation (HDE)

$$\frac{\partial}{\partial x} \left(k \frac{\partial T}{\partial x} \right) + \frac{\partial}{\partial y} \left(k \frac{\partial T}{\partial y} \right) + \frac{\partial}{\partial z} \left(k \frac{\partial T}{\partial z} \right) + \dot{q} = \rho c_p \frac{\partial T}{\partial t}$$

 For a plane 1D wall, steady state, and no heat generation, the HDE becomes

$$\frac{\partial}{\partial x} \left(k \frac{\partial T}{\partial x} \right) = 0$$

The general solution of this ordinary differential equation is

$$T(x) = C_1 x + C_2$$

where C_1 and C_2 are some constants determined by boundary conditions.

- The constants C_1 and C_2 may be determined by applying a constant surface temperature boundary condition to each wall surface located at 0 and L.
- This yields

$$C_1 = \frac{T_{s,2} - T_{s,1}}{I} \qquad C_2 = T_{s,1}$$

where $T_{s,1}$, and $T_{s,2}$ is the surface temperature at the wall surface located at 0 and L, respectively.

Substituting these into the temperature distribution expression shows

$$T(x) = (T_{s,2} - T_{s,1}) \frac{X}{L} + T_{s,1}$$

Thermal Resistance $T(x) = (T_{s,2} - T_{s,1}) \frac{x}{L} + T_{s,1}$

$$T(x) = (T_{s,2} - T_{s,1}) \frac{X}{L} + T_{s,1}$$

 With this temperature distribution expression, we can see how conduction behaves

$$q = -k A \frac{\partial T}{\partial x} = -k A \frac{\partial}{\partial x} [(T_{s,2} - T_{s,1}) \frac{x}{L} + T_{s,1}] = \frac{k A}{L} (T_{s,1} - T_{s,2})$$

Rearranging shows

$$\frac{T_{s,1} - T_{s,2}}{q} = \frac{L}{k A}$$

This is what is known as thermal resistance for conduction.

$$R_{t,cond} = \frac{T_{s,1} - T_{s,2}}{q} = \frac{L}{kA}$$

Thermal Resistance $R_{t,cond} = \frac{T_{s,1} - T_{s,2}}{a} = \frac{L}{kA}$

$$R_{t,cond} = \frac{T_{s,1} - T_{s,2}}{q} = \frac{L}{kA}$$

Let's look at the units

$$\frac{K}{W}[=]\frac{K}{\frac{J}{s}}[=]\frac{m}{(\frac{W}{mK})(m^2)}[=]\frac{m}{\frac{Wm}{K}}[=]\frac{K}{W}[=]\frac{K}{\frac{J}{s}}$$

Recall that electrical resistance is given by

$$R = \frac{\rho L}{A} = \frac{V}{I}$$

 A few analogies may be made to equate certain thermal elements to electrical elements

<u>Type</u>	<u>Electrical</u>	<u>Thermal</u>
Resistance	R	$R_{t,cond}$
Flow	I	q
Potential	V	T

- This may be applied to other modes of heat transfer.
- Convection

$$R_{t,conv} = \frac{T_s - T_{\infty}}{q} = \frac{1}{h A}$$

Radiation between a surface and large surroundings

$$R_{t,rad} = \frac{T_s - T_{sur}}{q} = \frac{1}{h_r A}$$

where h_r is the radiation heat transfer coefficient and is given by

$$h_r = \varepsilon \, \sigma (T_s + T_{sur}) (T_s^2 + T_{sur}^2)$$

Composite Wall (series)

- Consider the composite wall shown to the right.
- The thermal resistance of wall A, B, and C is given by

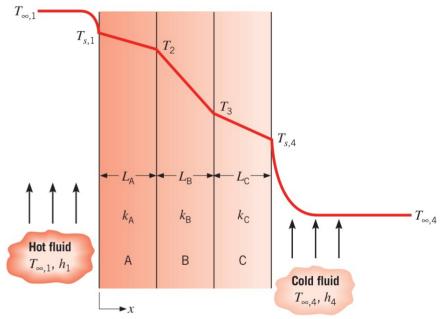
$$R_A = \frac{L_A}{k_A A}$$
 $R_B = \frac{L_B}{k_B A}$ $R_C = \frac{L_C}{k_C A}$

 The thermal resistance of the two convection boundaries are

$$R_1 = \frac{1}{h_1 A}$$
 $R_4 = \frac{1}{h_4 A}$

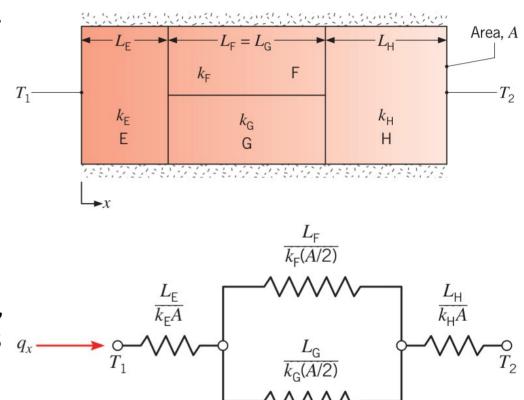
- The thermal circuit may then be drawn as

• The heat rate is then
$$q_x = \frac{T_{\infty,1} - T_{\infty,4}}{\sum R_t}$$



Composite Wall (parallel)

- A similar approach may be used for conduction in parallel.
- Consider the composite wall to the upper right.
- The equivalent thermal circuit would be as shown to the lower right.
- Remember from the initial analysis, 1D conduction was assumed so it is assumed that there is no heat transfer between wall F and G.



Composite Wall

- It is often convenient to work with an overall heat transfer coefficient.
- It is often denoted as U so

$$q = U A \Delta T$$

• *U* may then be defined as

$$U = \frac{1}{R_{tot}A}$$

• Or more often represented as

$$R_{tot} = \sum R_t = \frac{1}{IJA}$$

• R_{tot} would be equivalent to R_{eq} in an electrical circuit.

Example 1

Consider a person that has a layer of skin/fat covered with a special sporting gear suit, with the outer surface exposed to air at a temperature of 10 °C with a convective heat transfer coefficient of $2 W/m^2 K$. The inner surface (under the layer of skin/fat) is maintained at a constant temperature of 35 °C through a process called thermoregulation. The skin/fat layer has a thickness of 3 mm and an effective thermal conductivity of 0.3 W/mK. The total surface area of the skin/fat is 1.8 m^2 . The special sporting gear suit has a thermal conductivity of 0.014~W/mK. The emissivity of the outer surface of the special sporting gear suit is 0.95. What thickness of the sporting gear suit is needed to reduce the heat loss rate to 100 W? What is the resulting skin temperature? $T_i = 35^{\circ} \text{C}$

 $k_{\rm sf} = 0.3 \text{ W/m} \cdot \text{K}$

 $|-L_{\rm ef}| = 3 \text{ mm} - |-L_{\rm inc}|$

 $k_{\rm ins} = 0.014 \text{ W/m} \cdot \text{K}$

10/18

Contact Resistance

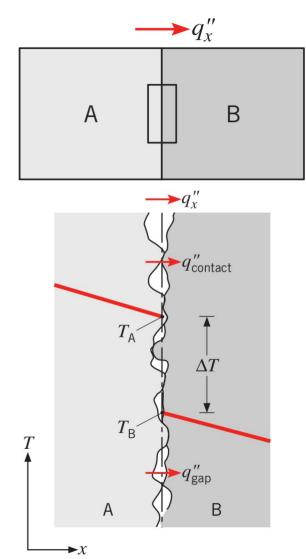
- Whenever composite materials are arranged, there exists a finite temperature drop across the touching surfaces of the materials.
- This finite temperature drop may be equated to a thermal contact resistance per unit area, $R_{tc}^{"}$.

$$R_{t,c}^{''} = \frac{T_A - T_B}{q''}$$

- The thermal contact resistance is a function of many different factors:
 - Material
 - Surface finish
 - Contact pressure
 - Interfacial fluid

Contact Resistance

- Consider the two materials shown to the upper right.
- If a section of the interface is closely examined, it may appear as the lower image shown to the right.
- As can be seen, there appears to points where there is material A to material B contact.
- However, there are also gaps.
- Heat will transfer differently at these locations.
- The effective (or "average") heat transfer is what causes thermal contact resistance.



Contact Resistance

- Empirical studies have been conducted to determine thermal contact resistance.
- For vacuum interfaces at different contact pressures

Table 5.1

Material	100 (kPa)	10,000 (kPa)
Stainless Steel	6-25	0.7-4.0
Copper	1-10	0.1-0.5
Magnesium	1.5-3.5	0.2-0.4
Aluminum	1.5-5.0	0.2-0.4

where values are $R_{t,c}^{"} \times 10^4 \, (m^2 K/W)$

• For aluminum interface ($10 \mu m$ surface roughness, 10 kPa contact pressure)

Table 5.2

Interfacial Fluid	$R''_{t,c} \times 10^4 (m^2 K/W)$
Air	2.75
Helium	1.05
Hydrogen	0.720
Silicone Oil	0.525
Glycerine	0.265

Example 2

A composite wall separates combustion gases at $2600 \, ^{\circ}C$ from a liquid coolant at $100 \, ^{\circ}C$, with gas and liquid side convection coefficients of $50 \, \text{and} \, 1000 \, \text{W/m}^2 \text{K}$, respectively. The wall is composed of $10 \, \text{mm}$ thick layer of beryllium oxide on the gas side and a $20 \, \text{mm}$ thick slab of stainless steel (AISI 304) on the liquid side. The contact resistance between the oxide and the steel is $0.05 \, \text{m}^2 \text{K/W}$. What is the heat lost per unit surface area of the composite? Sketch the temperature distribution from the gas to the liquid.

Porous Materials

- Consider a material that consists of pockets of stationary solid and fluid states.
- The heat transfer may be expressed as

$$q = \frac{k_{\it eff}\,A}{L}(T_{\it 1} - T_{\it 2})$$
 where $k_{\it eff}$ is the effective thermal conductivity.

- Let k_s and k_f represent the thermal conductivity of the solid and fluid portions, respectively.
- Let ε represents the fluid volume fraction (fluid volume over total volume).
- The porous material may then be represented two different ways.

Area A

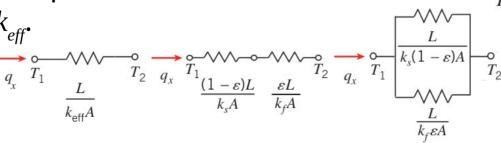
Porous Materials

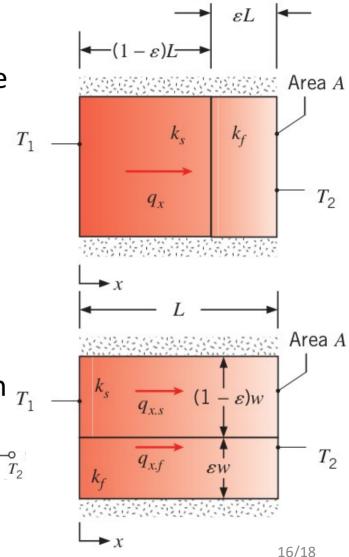
• The first representation is as if two materials are in series, the $k_{\rm eff}$ term is then

$$k_{eff,min} = \frac{1}{\frac{1-\varepsilon}{k_s} + \frac{\varepsilon}{k_f}}$$

• The second representation is as if two materials are in parallel, the $k_{\it eff}$ terms is then $k_{\it eff,max} = \varepsilon k_{\it f} + (1-\varepsilon)k_{\it s}$

• This approach provides minimum and maximum values for k_{off} .





Example 3

A batt of glass fiber insulation has a density of 28 kg/m^3 . Determine the maximum and minimum possible values of the effective thermal conductivity of the insulation at a temperature of 300 K. How does this compare to the values reported in Table A.3?

Cylindrical Systems

• A similar approach as the 1D plane wall may be used to derived the thermal resistance in a cylindrical system.

$$R_{t,cond} = \frac{\ln(\frac{r_2}{r_1})}{2\pi k L}$$

$$R_{t,conv} = \frac{1}{h \, 2 \, \pi r \, L}$$

